## Data Sheet

## Description

The AMMP-6430 MMIC is a broadband 1W power amplifier in a surface mount package designed for use in transmitters that operate in various frequency bands between 27 GHz and 34 GHz . At 30 GHz , it provides 29 dBm of output power ( $\mathrm{P}-1 \mathrm{~dB}$ ) and 19 dB of small-signal gain from a small easy-to-use device. The device has input and output matching circuitry for use in $50 \Omega$ environments. The AMMP-6430 also integrates a temperature compensated RF power detection circuit that enables power detection of $0.3 \mathrm{~V} / \mathrm{W}$. DC bias is simple and the device operates on widely available 5 V for current supply (negative voltage only needed for Vg ). It is fabricated in a PHEMT process for exceptional power and gain performance.

## Package Diagram



Note:

1. This MMIC uses depletion mode pHEMT devices. Negative supply is used for DC gate biasing.

## Features

- Wide Frequency Range $27-34$ GHz
- Half watt output power
- $50 \Omega$ match on input and output
- Specifications (Vd=5V, Idq=650mA)
- Frequency range 27 to 34 GHz
- Small signal Gain of 20 dB
- Output power @P-1 of 27 dBm (Typ.)
- Input/Output return-loss of -10 dB


## Applications

- Microwave Radio systems
- Satellite VSAT, DBS Up/Down Link
- LMDS \& Pt-Pt mmW Long Haul
- Broadband Wireless Access (including 802.16 and 802.20 WiMax)
- WLL and MMDS loops


## Functional Block Diagram



Attention: Observe Precautions for handling electrostatic sensitive devices. ESD Machine Model (Class A): 50V ESD Human Body Model (Class 0): 150V Refer to Avago Application Note A004R: Electrostatic Discharge Damage and Control.

Notes: MSL Rating = Level 2A

## Electrical Specifications

1. Small/Large -signal data measured in a fully de-embedded test fixture form $\mathrm{TA}=25^{\circ} \mathrm{C}$.
2. Pre-assembly into package performance verified $100 \%$ on-wafer.
3. This final package part performance is verified by a functional test correlated to actual performance at one or more frequencies.
4. Specifications are derived from measurements in a $50 \Omega$ test environment. Aspects of the amplifier performance may be improved over a more narrow bandwidth by application of additional conjugate, linearity, or low noise (Гopt) matching.
5. The Gain and P1dB tested at 27 GHz guaranteed with measurement accuracy $+/-1.5 \mathrm{~dB}$ for Gain and $+/-1.6 \mathrm{GHz}$ for P1dB.

## Table 1. RF Electrical Characteristics

$\mathrm{TA}=25^{\circ} \mathrm{C}, \mathrm{Vd}=5.0 \mathrm{~V}, \mathrm{Idq}=650 \mathrm{~mA}, \mathrm{Vg}=-1.1 \mathrm{~V}, \mathrm{Zo}=50 \Omega$

| Parameter | Min | Typ. | Max | Unit |
| :--- | :--- | :--- | :--- | :--- |
| Operational Frequency, Freq | 27 |  | 34 | GHz |
| Small-signal Gain Freq = 27GHz, Gain | 16 | 20 |  | dB |
| Output Power at 1dB Gain Compression, P1dB | 26 | 27 | dBm |  |
| Output Third Order Intercept Point, OIP3 |  | 35 | dBm |  |
| Input Return Loss, RLin | 10 | dB |  |  |
| Output Return Loss, RLout | 10 | dB |  |  |
| Reverse Isolation, Isolation | 43 | dB |  |  |

## Table 2. Recommended Operating Range

1. Ambient operational temperature $T A=25^{\circ} \mathrm{C}$ unless otherwise noted.
2. Channel-to-backside Thermal Resistance (Tchannel (Tch) $=34^{\circ} \mathrm{C}$ ) as measured using infrared microscopy. Thermal Resistance at backside temperature $(\mathrm{Tb})=25^{\circ} \mathrm{C}$ calculated from measured data.

| Description | Min. | Typical | Max. | Unit | Comments |
| :--- | :--- | :--- | :--- | :--- | :--- |
| Drain Supply Current, Idq |  | 650 |  | mA | $\mathrm{Vd}=5 \mathrm{~V}, \mathrm{Vg}$ set for Id Typical |
| Gate Voltage, Vg | -1.1 | V | Idq $=650 \mathrm{~mA}$ |  |  |

Table 3. Thermal Properties

| Parameter | Test Conditions | Value |
| :--- | :--- | :--- |
| Channel Temperature, Tch |  | $\mathrm{Tch}=139.6^{\circ} \mathrm{C}$ |
| Thermal Resistance | Ambient operational temperature $\mathrm{TA}=25^{\circ} \mathrm{C}$ <br> Channel-to-backside Thermal Resistance Tchannel $(\mathrm{Tch})=34^{\circ} \mathrm{C}$ | $\mathrm{R} \theta_{\mathrm{ch}-\mathrm{b}}=16.8^{\circ} \mathrm{C} / \mathrm{W}$ |
| Chase-Base Plate), R $\theta_{\text {ch-b }}$ | Thermal Resistance at backside temperature $\mathrm{Tb}=25^{\circ} \mathrm{C}$ |  |

Note:

1. Assume SnPb soldering to an evaluation RF board at $85^{\circ} \mathrm{C}$ base plate temperatures. Worst case is at saturated output power when DC power consumption rises to 5.24 W with 0.9 W RF power delivered to load. Power dissipation is 4.34 W and the temperature rise in the channel is $72.9^{\circ} \mathrm{C}$. In this condition, the base plate temperature must be remained below $82.1^{\circ} \mathrm{C}$ to maintain maximum operating channel temperature below 155 ${ }^{\circ} \mathrm{C}$.

Table 4. Absolete Minimum and Maximum Ratings

| Description | Min. | Max. | Unit | Comments |
| :--- | :--- | :--- | :--- | :--- |
| Drain Supply Voltage, Vd |  | 6 | V |  |
| Gate Supply Voltage, Vg | -3 | 0.5 | V |  |
| Drain Current, Idq | 900 | mA |  |  |
| Power Dissipation, Pd | 5.5 | W |  |  |
| CW Input Power, Pin | 23 | dBm | CW |  |
| Channel Temperature, Tch |  | +155 | ${ }^{\circ} \mathrm{C}$ |  |
| Storage Temperature, Tstg | -65 | +155 | ${ }^{\circ} \mathrm{C}$ |  |
| Maximum Assembly Temperature |  | +260 | ${ }^{\circ} \mathrm{C}$ | 20 second maximum |

## Notes:

1. Operation in excess of any one of these conditions may result in permanent damage to this device.
2. Combinations of supply voltage, drain current, input power, and output power shall not exceed PD.
3. When operate at this condition with a base plate temperature of $85^{\circ} \mathrm{C}$, the median time to failure (MTTF) is significantly reduced.
4. These ratings apply to each individual FET
5. Junction operating temperature will directly affect the device MTTF. For maximum life, it is recommended that junction temperatures be maintained at the lowest possible levels.

## AMMP-6430 Typical Performance

(Data obtained from $2.4-\mathrm{mm}$ connector based test fixture, and this data is including connecter loss, and board loss.) $\left(T_{A}=25^{\circ} \mathrm{C}, \mathrm{Vd}=5 \mathrm{~V}, \mathrm{Idq}=650 \mathrm{~mA}, \mathrm{~V}_{\mathrm{g}}=-1.1 \mathrm{~V}, \mathrm{Z}_{\text {in }}=\mathrm{Z}_{\text {out }}=50 \Omega\right)$


Figure 1. Typical Gain and Reverse Isolation


Figure 3. Typical P-1 and PAE


Figure 5. Typical IP3 (Third Order Intercept) @Pin=-20dBm


Figure 2. Typical Input \& Output Return Loss


Figure 4. Typical Pout, Ids, and PAE vs. Pin at Freq $=30 \mathrm{GHz}$


Figure 6. Typical Noise Figure


Figure 7. Typical Detector voltage vs. Output Power @30GHz


Figure 9. Typical S11 over temperature


Figure 11. Typical Gain over temperature


Figure 8. Typical S22 over temperature


Figure 10. Typical P-1 over temperature

## Typical Scattering Parameters ${ }^{[1]}$

$\left(\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{Vd}=5 \mathrm{~V}, \mathrm{I}_{\mathrm{dq}}=650 \mathrm{~mA}, \mathrm{Z}_{\text {in }}=\mathrm{Z}_{\text {out }}=50 \Omega\right)$

| Freq[GHz] | S11 |  |  | S21 |  |  | S12 |  |  | S22 |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | dB | Mag | Phase | dB | Mag | Phase | dB | Mag | Phase | dB | Mag | Phase |
| 1 | -0.077 | 0.991 | -30.672 | -60.460 | 0.001 | 156.200 | -81.678 | 8.24E-05 | 13.553 | -0.075 | 0.991 | -31.001 |
| 2 | -0.244 | 0.972 | -61.135 | -52.134 | 0.002 | 7.598 | -79.982 | 1.00E-04 | -1.433 | -0.218 | 0.975 | -61.826 |
| 3 | -0.507 | 0.943 | -91.481 | -55.059 | 0.002 | -178.810 | -78.816 | $1.15 \mathrm{E}-04$ | -26.240 | -0.450 | 0.949 | -92.759 |
| 4 | -0.857 | 0.906 | -121.770 | -62.791 | 0.001 | 135.030 | -73.965 | 2.00E-04 | -79.414 | -0.847 | 0.907 | -123.780 |
| 5 | -1.286 | 0.862 | -152.370 | -43.769 | 0.006 | 72.309 | -66.459 | $4.75 \mathrm{E}-04$ | -89.529 | -1.465 | 0.845 | -152.600 |
| 6 | -1.834 | 0.810 | 176.860 | -43.125 | 0.007 | -55.096 | -61.854 | 8.08E-04 | -141.380 | -1.593 | 0.832 | 177.570 |
| 7 | -2.497 | 0.750 | 146.160 | -47.710 | 0.004 | -138.310 | -59.371 | 1.08E-03 | -174.860 | -2.056 | 0.789 | 145.900 |
| 8 | -3.218 | 0.690 | 115.480 | -50.926 | 0.003 | 167.090 | -58.859 | $1.14 \mathrm{E}-03$ | 151.750 | -2.614 | 0.740 | 114.510 |
| 9 | -3.952 | 0.634 | 84.820 | -48.273 | 0.004 | 127.030 | -51.689 | 2.60E-03 | 128.260 | -3.234 | 0.689 | 82.673 |
| 10 | -4.734 | 0.580 | 54.869 | -47.156 | 0.004 | 82.462 | -49.760 | 3.25E-03 | 76.311 | -3.919 | 0.637 | 51.597 |
| 11 | -5.372 | 0.539 | 26.213 | -46.361 | 0.005 | 37.278 | -47.391 | $4.27 \mathrm{E}-03$ | 33.764 | -4.545 | 0.593 | 21.330 |
| 12 | -5.892 | 0.507 | -1.577 | -49.213 | 0.003 | 16.009 | -48.433 | $3.79 \mathrm{E}-03$ | -0.070 | -5.413 | 0.536 | -7.654 |
| 13 | -6.334 | 0.482 | -28.136 | -43.321 | 0.007 | -18.990 | -47.536 | $4.20 \mathrm{E}-03$ | -31.732 | -4.738 | 0.580 | -29.552 |
| 14 | -6.785 | 0.458 | -52.977 | -49.276 | 0.003 | -50.499 | -50.113 | $3.12 \mathrm{E}-03$ | -62.027 | -4.740 | 0.579 | -63.489 |
| 15 | -7.246 | 0.434 | -75.942 | -48.968 | 0.004 | -66.480 | -47.510 | $4.21 \mathrm{E}-03$ | -80.734 | -5.196 | 0.550 | -93.519 |
| 16 | -7.822 | 0.406 | -95.873 | -50.759 | 0.003 | 79.915 | -49.051 | $3.53 \mathrm{E}-03$ | -117.620 | -5.850 | 0.510 | -122.580 |
| 17 | -8.056 | 0.396 | -113.940 | -31.831 | 0.026 | 37.293 | -53.232 | 2.18E-03 | -135.710 | -6.891 | 0.452 | -151.530 |
| 18 | -8.011 | 0.398 | -130.700 | -19.650 | 0.104 | -11.371 | -54.404 | $1.90 \mathrm{E}-03$ | -136.240 | -8.605 | 0.371 | 179.660 |
| 19 | -8.003 | 0.398 | -150.530 | -8.565 | 0.373 | -65.975 | -52.389 | $2.40 \mathrm{E}-03$ | -100.790 | -11.491 | 0.266 | 151.610 |
| 20 | -8.086 | 0.394 | -172.380 | 2.944 | 1.404 | -130.730 | -45.317 | 5.42E-03 | -135.360 | -15.971 | 0.159 | 128.630 |
| 21 | -10.147 | 0.311 | 160.910 | 16.205 | 6.460 | 130.360 | -44.518 | 5.94E-03 | 179.470 | -32.906 | 0.023 | 80.680 |
| 22 | -10.495 | 0.299 | 156.560 | 19.584 | 9.533 | -6.027 | -44.477 | 5.97E-03 | 146.120 | -18.247 | 0.122 | -170.070 |
| 23 | -12.051 | 0.250 | 132.580 | 19.712 | 9.674 | -99.417 | -44.466 | 5.98E-03 | 129.370 | -18.242 | 0.122 | 169.400 |
| 24 | -15.378 | 0.170 | 122.010 | 20.404 | 10.476 | 174.220 | -44.254 | 6.13E-03 | 102.170 | -17.689 | 0.130 | 159.240 |
| 25 | -16.652 | 0.147 | 127.100 | 20.339 | 10.398 | 91.597 | -44.452 | 5.99E-03 | 63.925 | -18.009 | 0.126 | 147.290 |
| 26 | -17.111 | 0.139 | 113.670 | 19.880 | 9.862 | 16.978 | -44.351 | 6.06E-03 | 36.998 | -19.138 | 0.110 | 134.330 |
| 27 | -23.026 | 0.071 | 100.620 | 20.040 | 10.046 | -54.022 | -45.333 | 5.41E-03 | 1.733 | -23.261 | 0.069 | 137.140 |
| 28 | -20.256 | 0.097 | 166.160 | 20.218 | 10.255 | -128.560 | -52.770 | $2.30 \mathrm{E}-03$ | -49.664 | -18.834 | 0.114 | 161.640 |
| 29 | -14.571 | 0.187 | 152.630 | 20.087 | 10.100 | 157.600 | -49.161 | $3.48 \mathrm{E}-03$ | -75.571 | -15.869 | 0.161 | 147.670 |
| 30 | -13.363 | 0.215 | 128.640 | 19.761 | 9.729 | 85.669 | -57.520 | $1.33 \mathrm{E}-03$ | 15.834 | -15.535 | 0.167 | 128.380 |
| 31 | -11.814 | 0.257 | 107.980 | 19.830 | 9.807 | 10.808 | -86.823 | 4.56E-05 | -92.886 | -14.211 | 0.195 | 109.870 |
| 32 | -10.715 | 0.291 | 83.770 | 19.352 | 9.282 | -68.718 | -58.807 | $1.15 \mathrm{E}-03$ | -82.154 | -13.484 | 0.212 | 82.184 |
| 33 | -10.889 | 0.285 | 65.105 | 18.619 | 8.531 | -150.100 | -62.898 | 7.16E-04 | 92.036 | -14.452 | 0.189 | 72.563 |
| 34 | -11.417 | 0.269 | 41.069 | 18.093 | 8.028 | 124.500 | -51.835 | 2.56E-03 | -4.332 | -15.301 | 0.172 | 53.869 |
| 35 | -12.098 | 0.248 | 36.792 | 15.162 | 5.730 | 14.850 | -52.719 | $2.31 \mathrm{E}-03$ | -115.640 | -12.933 | 0.226 | 56.976 |
| 36 | -11.897 | 0.254 | 24.365 | 7.101 | 2.265 | -75.509 | -58.568 | $1.18 \mathrm{E}-03$ | -48.164 | -12.205 | 0.245 | 32.346 |
| 37 | -11.125 | 0.278 | 13.967 | -0.825 | 0.909 | -142.060 | -57.430 | $1.34 \mathrm{E}-03$ | -124.980 | -12.066 | 0.249 | 15.583 |
| 38 | -10.020 | 0.316 | -0.758 | -7.753 | 0.410 | 161.700 | -52.497 | $2.37 \mathrm{E}-03$ | -154.340 | -11.605 | 0.263 | 0.967 |
| 39 | -9.222 | 0.346 | -16.019 | -13.812 | 0.204 | 110.760 | -56.625 | $1.47 \mathrm{E}-03$ | 116.090 | -11.065 | 0.280 | -12.574 |
| 40 | -8.609 | 0.371 | -32.089 | -19.209 | 0.110 | 62.155 | -55.294 | $1.72 \mathrm{E}-03$ | 91.256 | -10.402 | 0.302 | -26.857 |
| 41 | -8.175 | 0.390 | -47.230 | -24.340 | 0.061 | 13.948 | -56.805 | $1.44 \mathrm{E}-03$ | 1.705 | -9.889 | 0.320 | -40.144 |
| 42 | -7.588 | 0.417 | -62.593 | -29.416 | 0.034 | -31.372 | -57.472 | $1.34 \mathrm{E}-03$ | -87.233 | -9.293 | 0.343 | -52.531 |
| 43 | -7.587 | 0.417 | -78.246 | -34.254 | 0.019 | -72.562 | -64.193 | 6.17E-04 | -136.190 | -8.532 | 0.374 | -64.211 |
| 44 | -7.506 | 0.421 | -89.361 | -38.657 | 0.012 | -112.560 | -69.135 | $3.49 \mathrm{E}-04$ | -109.180 | -7.654 | 0.414 | -77.188 |
| 45 | -7.332 | 0.430 | -101.290 | -43.475 | 0.007 | -145.910 | -60.759 | 9.16E-04 | -29.843 | -7.062 | 0.444 | -90.938 |

Note:

1. Data obtained from a $2.4-\mathrm{mm}$ connecter based module, and this data is including connecter loss, and board loss.

## Biasing and Operation

Recommended quiescent DC bias condition for optimum power and linearity performances is $\mathrm{Vd}=5$ volts with $\mathrm{Vg}(-1.1 \mathrm{~V})$ set for $\mathrm{Id}=650 \mathrm{~mA}$. Minor improvements in performance are possible depending on the application. The drain bias voltage range is 3 to 5 V . A single DC gate supply connected to Vg will bias all gain stages. Muting can be accomplished by setting Vg to the pinch-off voltage Vp .
A simplified schematic for the AMMP6430 MMIC die is shown in Figure 12. The MMIC die contains ESD and over voltage protection diodes for Vg , and Vd terminals. The package diagram for the recommended assembly is shown in Figure 13. In finalized package form, ESD diodes protect all possible ESD or over voltage damages between Vgg and ground, Vg and Vd , Vd and ground. Typical ESD diode current versus diode voltage for 11connected diodes in series is shown in Figure 14. Under the recommended $D C$ quiescent biasing condition at $\mathrm{Vds}=5 \mathrm{~V}$, Ids $=650 \mathrm{~mA}, \mathrm{Vg}=-1 \mathrm{~V}$, typical gate terminal current is approximately 0.3 mA . If an active biasing technique is selected for the AMMP6430 MMIC PA DC biasing, the active biasing circuit must have more than 10-times higher internal current that the gate terminal current.

An optional output power detector network is also provided. The differential voltage between the Det-Ref and Det-Out pads can be correlated with the RF power
emerging from the RF output port. The detected voltage is given by :

$$
V=\left(V_{\text {ref }}-V_{\text {det }}\right)-V_{\text {ofs }}
$$

where $\mathrm{V}_{\text {ref }}$ is the voltage at the DET_R port, $\mathrm{V}_{\text {det }}$ is a voltage at the DET_0 port, $\mathrm{V}_{\text {ofs }}$ and is the zero-inputpower offset voltage.

There are three methods to calculate $\mathrm{V}_{\text {ofs }}$ :

1. $V_{\text {ofs }}$ can be measured before each detector measurement (by removing or switching off the power source and measuring $\mathrm{V}_{\text {ref }}-\mathrm{V}_{\text {det }}$ ). This method gives an error due to temperature drift of less than $0.01 \mathrm{~dB} / 50^{\circ} \mathrm{C}$.
2. $V_{\text {ofs }}$ can be measured at a single reference temperature. The drift error will be less than 0.25 dB .
3. $V_{\text {ofs }}$ can either be characterized over temperature and stored in a lookup table, or it can be measured at two temperatures and a linear fit used to calculate $\mathrm{V}_{\text {ofs }}$ at any temperature. This method gives an error close to the method \#1.

The RF ports are AC coupled at the RF input to the first stage and the RF output of the final stage. No ground wired are needed since ground connections are made with plated through-holes to the backside of the device.


Figure 12. Simplified schematic for the MMIC die


| Pin | Function |
| :---: | :---: |
| 1 | Vg |
| 2 | Vd |
| 3 | DET_O |
| 4 | RF_out |
| 5 | DET_R |
| 6 | Vd |
| 7 | Vg |
| 8 | RF_in |

Note:

1. Vd may be applied to either Pin 2 or $\operatorname{Pin} 6$.
2. Vg may be applied to either Pin 1 or Pin 7.

Figure 13. Schematic for recommended Bias circuitry


Figure 14. Typical ESD diode current versus diode voltage for 11-connected diodes in series

AMMP-6430 Part Number Ordering Information

| Part Number | Devices Per <br> Container | Container |
| :--- | :--- | :--- |
| AMMP-6430-BLKG | 10 | Antistatic bag |
| AMMP-6430-TR1G | 100 | 7" Reel |
| AMMP-6430-TR2G | 500 | 7" Reel |

## Package Dimension, PCB Layout and Tape and Reel information

Please refer to Avago Technologies Application Note 5520, AMxP-xxxx production Assembly Process (Land Pattern A).

